

MEMS Engineer Forum 2023

SMART Society Driven by MEMS

April 19-20, 2023

KFC Hall, Ryogoku, Tokyo, Japan

Free charge for conference and exhibition

MEF 2023 will be held
In-person format



EXHIBIT Guidance

<http://www.m-e-f.info/>

Exhibits Type and Benefit (10% tax to be added)	Regular Exhibit	Academic Exhibit	Start-up Exhibit
	¥250,000	¥50,000	¥50,000
1 Short Presentation	○	×	○
2 Advertisement in digital MEF Program Handout	A4 Full page○	A4 Full page○	A4 Full page○
3 Logo on MEF Website	○	○	○
4 Logo on MEF Sign board	○	○	○
5 1-min PR Movie Run at breaktime (main hall)	○	×	○
6 Invitation ticket(s) to Networking event (Apr. 19)	1*	×	×
7 Lunch ticket(s) (Apr.19&20)	2*	×	×
8 Meeting room usage	○	○	○

In case that the event is changed to full online, the alternative benefit will be provided.
*If you apply by February 10, 2023, your invitation slot will be doubled!.

Speaker for MEF2023

Alphabetical order by last name

Ichiro Amimori, Xenoma Inc. (Japan)
Sonia Costantini, STMicroelectronics (Italy)
Weileun Fang, National Tsing Hua University (Taiwan)
Alissa M. Fitzgerald, A.M. Fitzgerald & Associates, LLC. (USA)
Peter Hartwell, TDK-InvenSense (USA)
Susumu Kaminaga, SPP Technologies Co., Ltd./SK Global Advisers Co., Ltd. (Japan)
Thomas Kenny, Stanford University (USA)
Takashi Kitahara, TESEC Corporation (Japan)
Jerome Mouly, Yole Developpement (France)
Thomas Otto, Fraunhofer ENAS (Germany)
Kurt Petersen, Silicon Valley Band of Angels (USA)
Philippe Robert, CEA-Leti (France)
Florian Schuster, Robert Bosch GmbH (Hungary)
Tetsuya Tanaka, Ricoh (Japan)
Kiyoshi Toko, Kyushu University (Japan)
Gerald Yin, AMEC (China)
Koichi Yoshida, Kanazawa Murata Manufacturing Co., Ltd. (Japan)

and more speakers to be announced.

MEF International Advisory Committee

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Hiroki Kuwano/Tohoku University
Vice Chair
Masayoshi Esashi/Tohoku University
Susumu Kaminaga/SPP Technologies/SK Global Advisers
Naoto Kobayashi/Waseda University
Committee Member
Jean-Christophe Eloy/Yole Developpement
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Udo-Martin Gomez/Robert Bosch
Thomas Kenny/Stanford University
Xinxin Li/Shanghai Institute of Microsystem and Information Technology
Hiroshi Miyajima/Sumitomo Precision Products
Yutakata Nonomura/Meijo University
Kurt Petersen/Silicon Valley Band of Angels

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Masaki Hirose/Hamamatsu Photonics K.K.
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Yoshiaki Kanamori/Tohoku University
Nobuaki Kawahara/Denso Corporation
Akihiro Koga/Canon Medical Systems Corporation
Osamu Koyanagi/Nippon Investment Company
Masahiro Mita/Kyodo International Inc.
Mitsugu Ogiura/Murata Manufacturing Co., Ltd.
Yoshiaki Oku/ROHM Co., Ltd.
Kazuaki Sawada/Toyohashi University of Technology
Tomonori Seki/OMRON Corporation
Takehisa Takoshima/Tohoku University
Toshiyuki Tsuchiya/Kyoto University
Yoko Yamanishi/Kyushu University
Takashi Yoshida/Yokogawa Electric Corporation

Regular Booth

Booth size: W1800mm × D900mm × H2100mm
(Height of table: 700mm)

The following items are included in the booth.

- Back panel
- Affiliation Name Board (standardized design)
- Electric outlet 500W (2 outlets)
- Table and Chair

Academic and Start-up Booth

Booth size: W1800mm × D450mm × H1800mm
(Height of table: 700mm)

The following items are included in the booth.

- Back panel
- Affiliation Name Board (standardized design)
- Table and Chair
- Electric outlet 500W (2 outlets) is optional.

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